

International Application No.: PCT/JP2004/017173

U.S. Patent Application No.: Unknown

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Page 3 of 10

**IN THE ABSTRACT:**

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following Abstract:

#### ABSTRACT OF THE DISCLOSURE

A laminated ceramic electronic component includes a plurality of conductor pattern layers ~~(2, 3, and 4)~~ for a coil ~~overlaps~~arranged to overlap each other to form substantially U-shaped conductors ~~(2A, 3A, and 4A)~~ for the coil. The conductors ~~(2A, 3A, and 4A)~~ for the coil are electrically connected in series ~~with~~through via holes ~~(15)~~ for ~~inter~~inner layer connection provided in ceramic green sheets ~~(10 and 11)~~ to form a spiral coil ~~(L)~~. A plurality of leading conductor pattern layers ~~(5 and 6)~~ also overlaps each other to form leading conductors ~~(5A and 6A)~~. One leading conductor pattern layer ~~(5)~~ is disposed per a predetermined number of conductor pattern layers ~~(2)~~ for the coil. An end ~~(51)~~ of each leading conductor pattern layer ~~(5)~~ is in contact with the corresponding conductor pattern layer ~~(2)~~ for the coil. In other words, the thickness of the leading conductors ~~(5A and 6A)~~ is smaller~~less~~ than the thickness of the conductors ~~(2A to 4A)~~ for the coil.